WIREBONDING CHECKLIST FOR CMS TOB HYBRIDS

Program: CMS-CH2 or CMS-CHI

Part Orientation:

1. Pitch Adapter to Chip Bonds

**Lead Reference System (L):** Pitch Adapter  
**Die Reference System (U):** Chip

- **First Bond: Pitch Adapter**
  - Bond time: 20 ms
  - USG Current: 60 to 75mA
  - Force: 20

- **Second Bond: Chip**
  - Bond time: 20 ms
  - USG Current: 48 to 55mA
  - Force: 35

**Loop Parameters:**
- Shape: square
- Loop height: short bonds 33 mils, long bonds 48 mils
- Clear height: short bonds 53 mils, long bonds 68 mils
- Clamp close at loop

**Tail Parameters:**
- Feed: 75
2. Hybrid Bias Bonds

Bias Bonds Location:

Pitch Adapter to Gold Pad on Hybrid:
Place 4 bonds, 2 short, 2 long

First Bond: Pitch Adapter
Bond time: 20ms
USG Current: 65 to 75mA
Force: 20

Second Bond: Gold
Bond time: 30 to 35 ms
USG Current: 60 to 70mA
Force: 25

Loop Parameters:
Shape: square
Loop height: short bonds 60 mils, longs bonds 70 mils
Clamp close at loop

Tail Parameters:
Feed: 75